CLAIMS

What is claimed is:

1. A method of adjusting the planarity of a substrate in a probe card assembly, the method comprising:

deflecting at least one of a first area of the substrate, a second area of the substrate, a third area of the substrate, and a fourth area of the substrate;

said deflecting comprising applying a pulling force to said at least one of said first, second, third, and fourth areas of the substrate.

2. A method as in claim 1 wherein at least said first area is a non-peripheral area of the substrate.

3. A method as in claim 1 wherein said deflecting further comprises applying a pushing force to at least one of said first, second, third, and fourth areas to which said pulling force is not applied.

4. A method as in claim 1 wherein said deflecting is performed manually.

5. A method as in claim 1 wherein said deflecting is performed automatically.

6. An interposer for use with a probe card assembly, the interposer comprising:

a non-peripheral opening capable of receiving an actuating assembly for deflecting a space transformer in the probe card assembly.

7. A method of achieving a degree of planarity among contact portions of a plurality of contact structures mounted to a substrate, the method comprising:

creating the substrate with the plurality of contact structures coupled to a first surface of the substrate, the contact portions of the contact structures having a first planar relationship relative to one another;

applying a plurality of forces selectively to the substrate to deform the substrate and achieve a second planar relationship of the contact portions of the contact structures relative to one another.

8. A method as in claim 7 wherein a plurality of substrates are deformed on a combined assembly.

9. A method as in claim 8 wherein a rotational adjustment is performed on at least one of the substrates in said combined assembly.

10. A method as in claim 8 wherein a translational adjustment is performed on at least one of the substrates in said combined assembly.